

Dual N-Channel Enhancement Mode MOSFET

1. Product Information

1.1 Features

- CSP package**
- Extremely low threshold voltage**
- Advanced trench cell design**
- ESD protected**

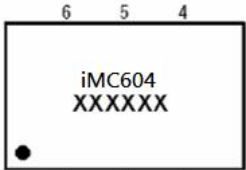
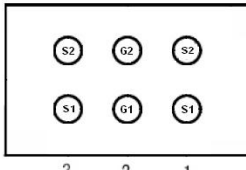
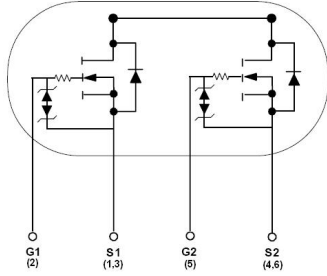
1.2 Applications

- Portable appliances**
- Battery management**

1.3 Quick reference

- BV** ≥ 12 V
- R_{SS(ON)}** ≤ 6.0 m Ω @ V_{GS} = 4.5 V
- P_{tot}** ≤ 3.8 W
- R_{SS(ON)}** ≤ 7.0 m Ω @ V_{GS} = 3.9 V
- I_S** ≤ 20 A
- R_{SS(ON)}** ≤ 8.5 m Ω @ V_{GS} = 2.5 V

2. Pin Description

Pin	Description	Simplified Outline	Symbol
1,3	Source(S1)	CSP Package  Top View  Bottom	
2	Gate(G1)		
4,6	Source(S2)		
5	Gate(G2)		

3. Limiting Values


Symbol	Parameter	Conditions	Min	Max	Unit
V _{SS}	Source-Source Voltage	T _A = 25 °C	12	-	V
V _{GS}	Gate-Source Voltage	T _A = 25 °C	-	± 10	V
I _S *	Source Current	T _A = 25 °C, V _{GS} = 4.5 V	-	20	A
I _{SM} **	Pulsed Source Current	T _A = 25 °C, V _{GS} = 4.5 V	-	80	A
P _{tot} *	Total Power Dissipation	T _A = 25 °C	-	3.8	W
		T _A = 70 °C	-	2.4	
T _{stg}	Storage Temperature		- 55	150	°C
T _J	Junction Temperature		-	150	°C
R _{θJA} *	Thermal Resistance- Junction to Ambient		-	32.8	°C / W

Notes :

* Surface Mounted on 1 in² pad area, t ≤ 10 sec

** Pulse width ≤ 10 μs, duty cycle ≤ 1 %

4. Marking Information

Product Name	Marking
KJ604C	

5. Ordering Code

Product Name	Package	Reel Size	Tape width	Quantity	Note
KJ604C	CSP			3000	

Note: KUAJIEXIN defines “ Green ” as lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900 ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500 ppm by weight; Follow IEC 61249-2-21 and IPC / JEDEC J-STD-020C)

6. Electrical Characteristics ($T_A = 25\text{ }^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static Characteristics						
BV_{SSS}	Source-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_S = 250\text{ }\mu\text{A}$	12	-	-	V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{SS} = 10\text{ V}, I_S = 250\text{ }\mu\text{A}$	0.5	-	1.0	V
I_{SSS}	Zero Gate Voltage Source Current	$V_{SS} = 10\text{ V}, V_{GS} = 0\text{ V}$	-	-	1	μA
		$T_J = 85\text{ }^\circ\text{C}$	-	-	30	μA
I_{GSS}	Gate Leakage Current	$V_{GS} = \pm 10\text{ V}, V_{DS} = 0\text{ V}$	-	-	± 10	μA
$R_{SS(ON)}^a$	Source-source On-State Resistance	$V_{GS} = 4.5\text{ V}, I_S = 5\text{ A}$	-	5	6	$\text{m}\Omega$
		$V_{GS} = 3.9\text{ V}, I_S = 4\text{ A}$	-	5.3	7	
		$V_{GS} = 2.5\text{ V}, I_S = 3\text{ A}$	-	6.8	8.5	
Diode Characteristics						
V_{FSS}^a	Diode Forward Voltage	$I_S = 5\text{ A}, V_{GS} = 0\text{ V}$	-	-	1.3	V
Dynamic Characteristics^b						
C_{iss}	Input Capacitance	$V_{GS} = 0\text{ V}, V_{SS} = 6\text{ V}$ Frequency = 1 MHz	-	3118	-	pF
C_{oss}	Output Capacitance		-	648	-	
C_{rss}	Reverse Transfer Capacitance		-	554	-	
$t_d(on)$	Turn-on Delay Time	$V_{SS} = 6\text{ V}, V_{GEN} = 4.5\text{ V},$ $R_G = 4.5\text{ }\Omega, R_L = 1.2\text{ }\Omega,$ $I_S = 5\text{ A}$	-	849	-	nS
t_r	Turn-on Rise Time		-	1798	-	
$t_d(off)$	Turn-off Delay Time		-	1216	-	
t_f	Turn-off Fall Time		-	5710	-	
Gate Charge Characteristics^b						
Q_g	Total Gate Charge	$V_{GS} = 4.5\text{ V}, V_{SS} = 10\text{ V},$ $I_S = 5\text{ A}$	-	54	-	nC
Q_{gs}	Gate-Source Charge		-	5.9	-	
Q_{gd}	Gate-Drain Charge		-	9.7	-	

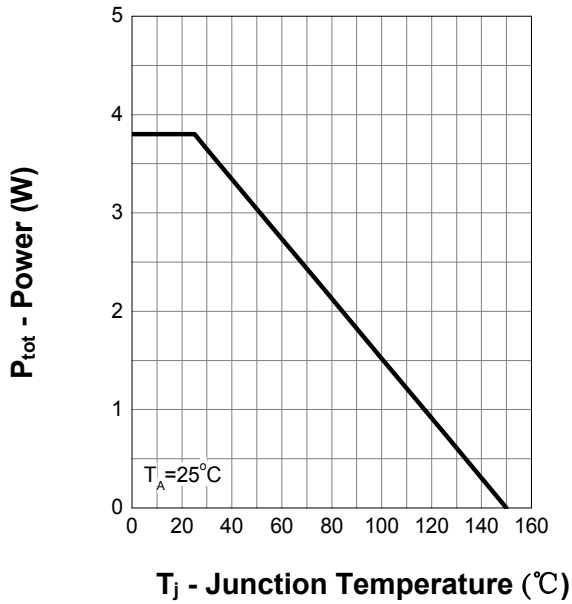
Notes :

a : Pulse test ; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$

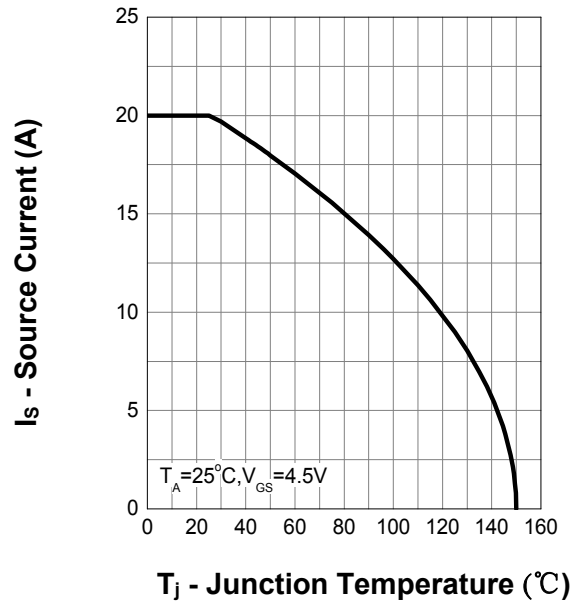
b : Guaranteed by design, not subject to production testing

7. Typical Characteristics

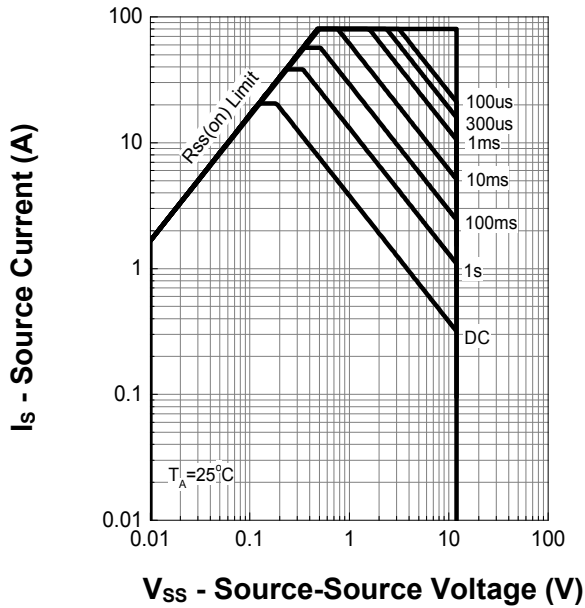
Power Dissipation



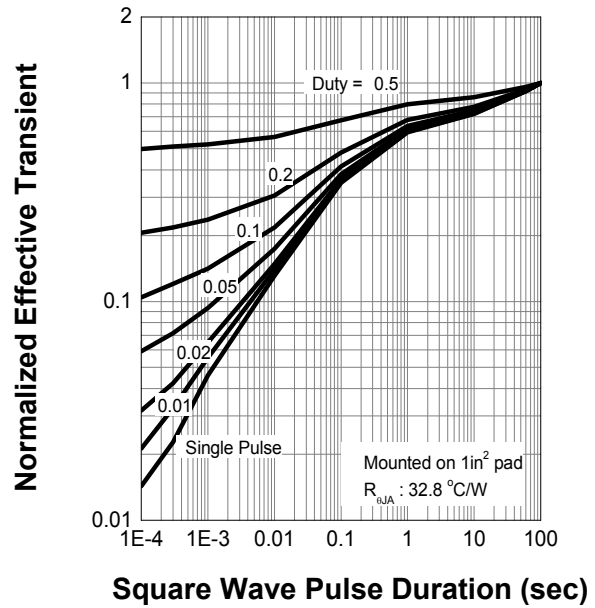
Source Current



Safe Operation Area

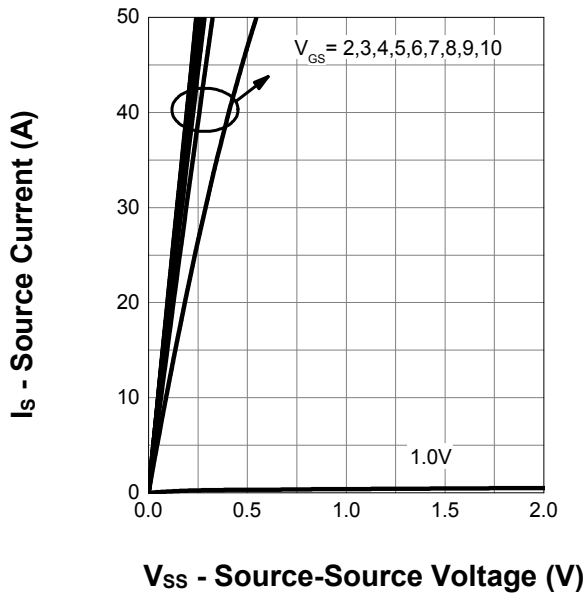


Thermal Transient Impedance

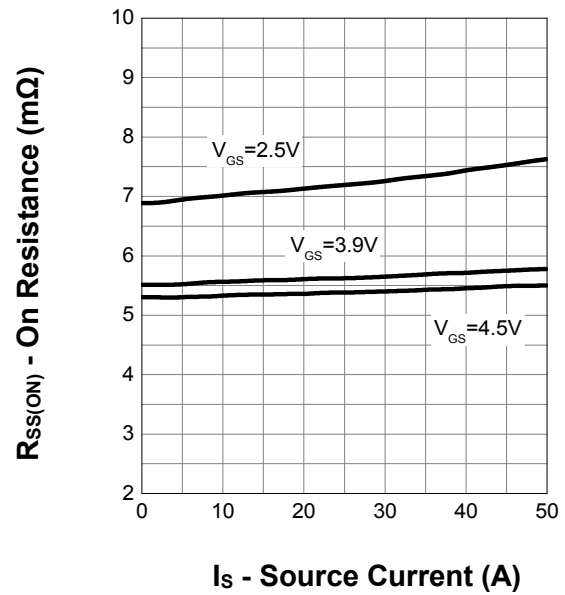


7. Typical Characteristics (cont.)

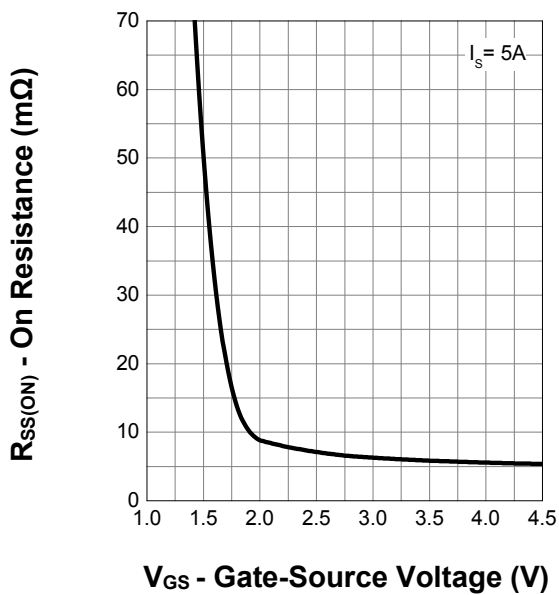
Output Characteristics



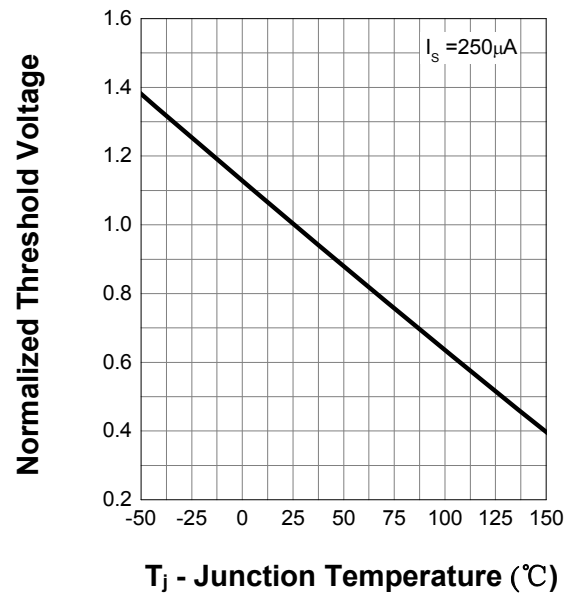
Source-Source On Resistance



Transfer Characteristics

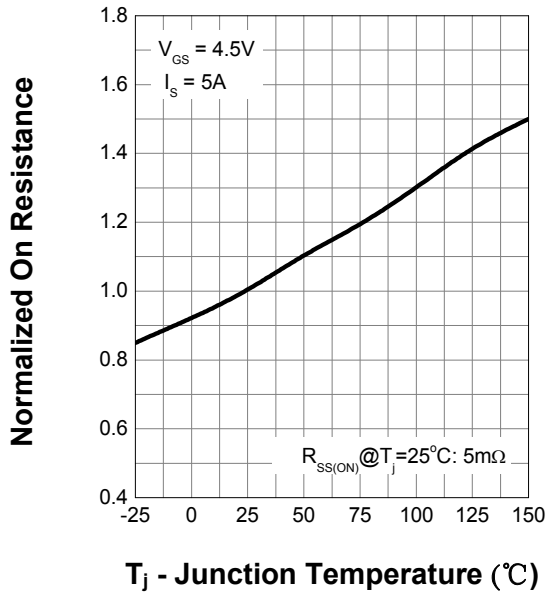


Gate Threshold Voltage

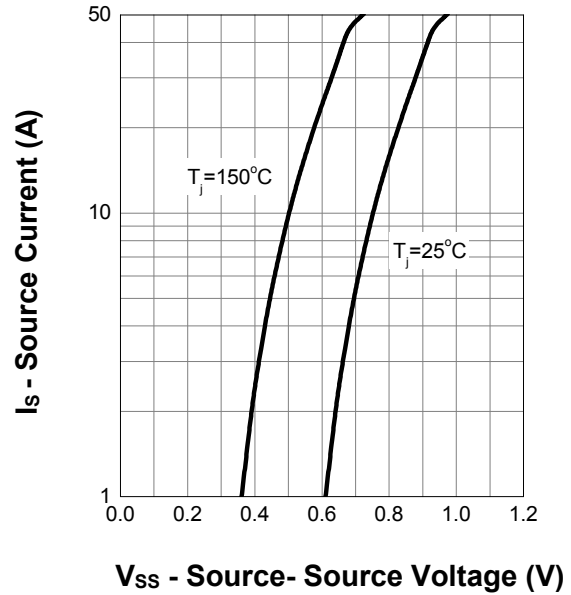


7. Typical Characteristics (cont.)

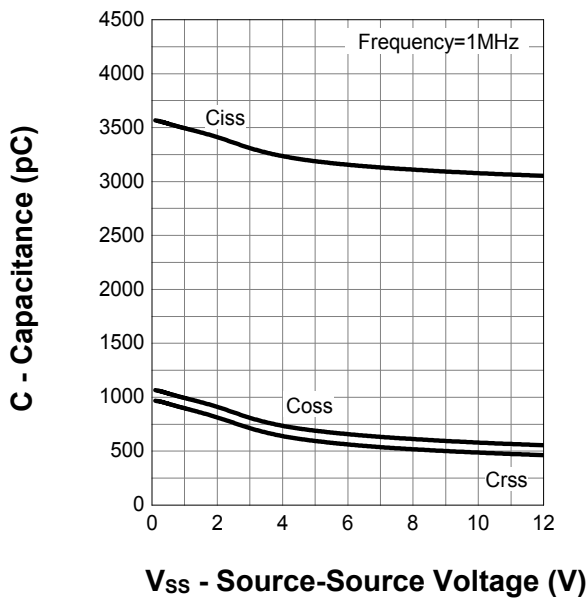
Source-Source On Resistance



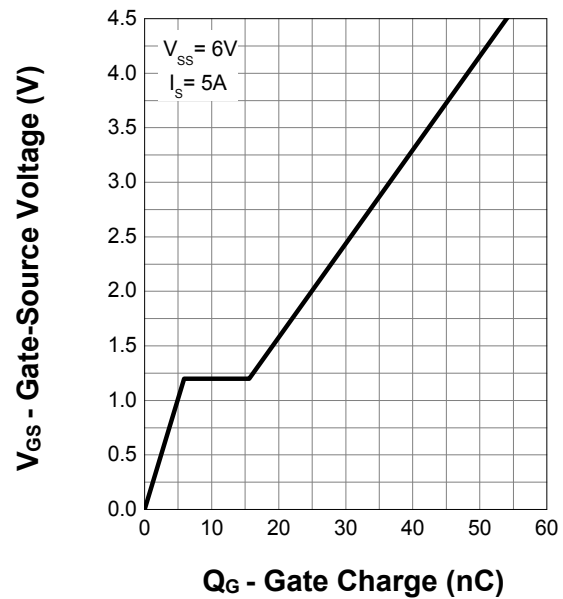
Body Diode Characteristics



Capacitance



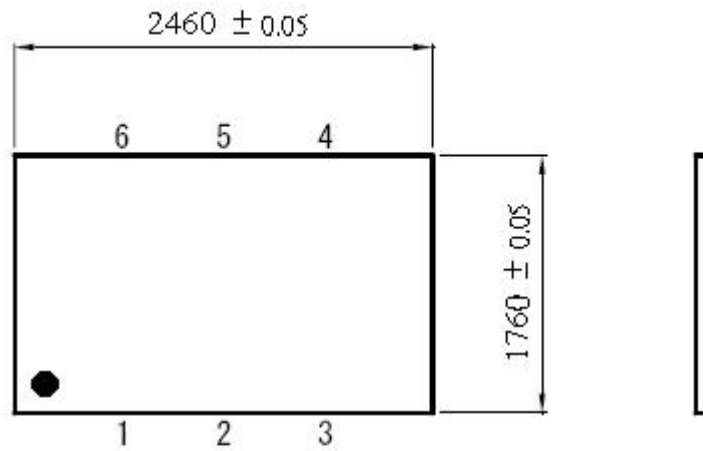
Gate Charge



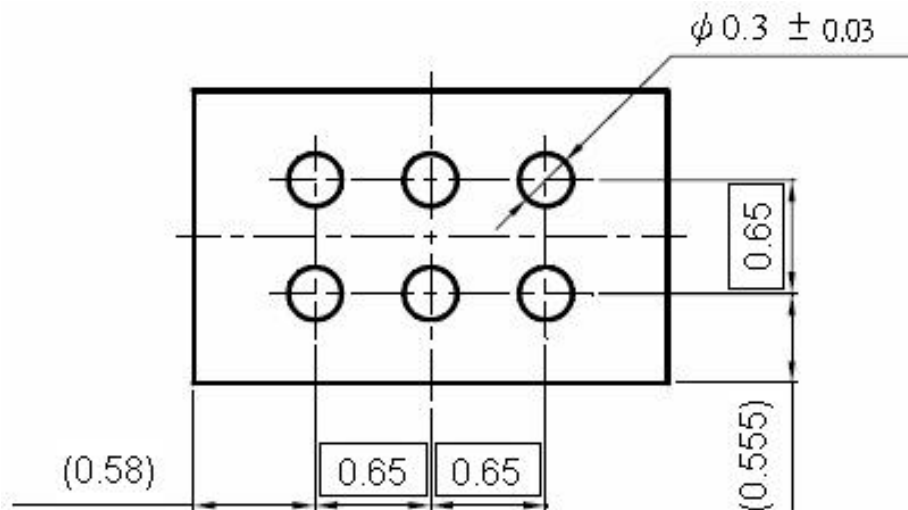
8.Package Dimensions

- Design Information

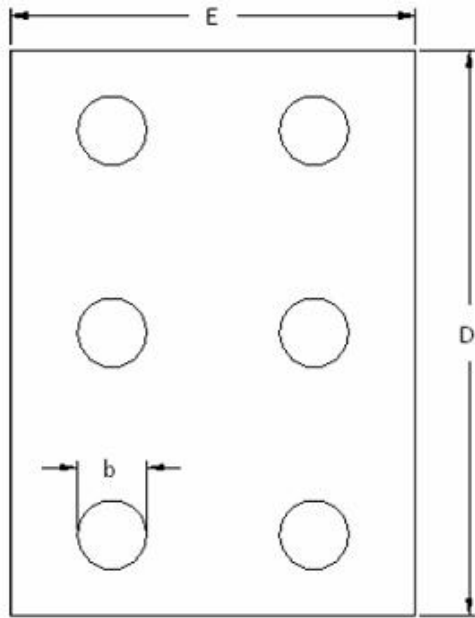
Unit: um



Unit: mm

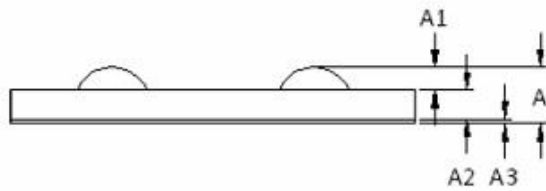


- Structure Information



SYMBOL	DIMENSION(mm)		
	MIN	NOM	MAX
A	0.145	0.195	0.245
A1	0.035	0.050	0.065
A2	0.095	0.125	0.155
A3	0.010	0.020	0.030
b	0.285	0.300	0.315
E	1.710	1.760	1.810
D	2.410	2.460	2.510

Min. Ball pitch : 0.650



- Ball Map (View : Chip side Up)



Pin Number	X Coord	Y Coord
S1	-325.00	650.00
S2	325.00	650.00
G1	-325.00	0.00
G2	325.00	0.00
S1	-325.00	-650.00
S2	325.00	-650.00